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Contents

vii	<i>Authors</i>
xi	<i>Conference Committee</i>
xv	<i>Introduction</i>

KEYNOTE AND INVITED SESSION

10451 02	Extending the era of Moore's Law (Keynote Paper) [10451-1]
10451 03	2017 mask maker survey conducted by the eBeam Initiative (Invited Paper) [10451-2]

MASK DATA PREPARATION I

10451 04	Manufacturing challenges for curvilinear masks (Invited Paper) [10451-3]
10451 05	VSB fracture optimization for mask write time reduction [10451-5]

MASK DATA PREPARATION II

10451 06	Adopting rigorous verification flow in fabrication of silicon photonic devices [10451-6]
10451 07	An efficient tool to rewrite a VSB12 format jobdeck for any target VSB12 machine [10451-7]
10451 08	Full-chip GPU-accelerated curvilinear EUV dose and shape correction [10451-8]
10451 09	CLMPC: curvilinear MPC in a mask data preparation flow [10451-9]

MACHINE LEARNING

10451 0A	Machine learning for mask/wafer hotspot detection and mask synthesis (Invited Paper) [10451-10]
10451 0C	Impact of feature extraction to accuracy of machine learning based hotspot detection [10451-12]
10451 0D	Machine learning assisted SRAF placement for full chip [10451-13]

PHOTOMASK JAPAN 2017

- 10451 OG **Fabrication of cylindrical micro-parts using synchronous rotary scan-projection lithography and chemical etching** [10451-15]
- 10451 OH **The capability of measuring cross-sectional profile for hole patterns in nanoimprint templates using small-angle x-ray scattering** [10451-16]

EUV MASK INSPECTION: JOINT SESSION WITH CONFERENCES 10451 AND 10450

- 10451 OJ **Actinic review of EUV masks: challenges and achievements in delivering the perfect mask for EUV production** [10451-18]
- 10451 OK **DUV inspection beyond optical resolution limit for EUV mask of hp 1X nm** [10451-19]
- 10451 OL **EUV reticle print verification with advanced broadband optical wafer inspection and e-Beam review systems** [10451-20]

EUV MASK PELLICLE: JOINT SESSION WITH CONFERENCES 10451 AND 10450

- 10451 OO **Pellicle films supporting the ramp to HVM with EUV** [10451-22]
- 10451 OP **CNT EUV pellicle: moving towards a full-size solution** [10451-23]
- 10451 OQ **Development of EUV pellicle for suppression of contamination, haze, and outgas generation** [10451-24]
- 10451 OR **EUV optical characterization of alternative membrane materials for EUV pellicles** [10451-25]
- 10451 OS **Rigorous simulation of EUV mask pellicle** [10451-26]

STUDENT SESSION: JOINT SESSION WITH CONFERENCES 10451 AND 10450

- 10451 OT **Enhanced critical feature representation for fuzzy-matching for lithography hotspot detection** [10451-37]

MASK/OPC INTERACTIONS

- 10451 OV **The impact of inconsistency in assist feature generation on OPC performance** [10451-60]
- 10451 OW **Edge placement errors in EUV from aberration variation** [10451-58]
- 10451 OX **Process window discovery from mask inspection for hotspot analysis and verification** [10451-30]
- 10451 OY **Estimated mask contours: potential applications** [10451-31]

METROLOGY

- 10451 0Z **Implementation of CDSEM contour extraction on OPC verification** [10451-32]
- 10451 10 **Selective measurement of small metrology targets using CD-GISAXS** [10451-33]
- 10451 11 **Off-line mask-to-mask registration characterization as enabler for computational overlay**
[10451-34]
- 10451 13 **Automated defect disposition with AIM AutoAnalysis** [10451-36]

PHOTOMASK LITHOGRAPHY, AND MASK PROCESS & REPAIR

- 10451 14 **Characterization of acoustic cavitation from a megasonic nozzle transducer for photomask cleaning** [10451-38]
- 10451 15 **Advanced photomask chrome etch: selectivity without sacrifice** [10451-39]
- 10451 16 **Improving back end of line productivity through smart automation** [10451-67]
- 10451 17 **Multi-beam mask writer MBM-1000** [10451-42]

NANO IMPRINT LITHOGRAPHY

- 10451 1A **Development of an inkjet-enabled adaptive planarization process** [10451-45]
- 10451 1B **Progress in nanoimprint wafer and mask systems for high volume semiconductor manufacturing** [10451-46]

POSTER SESSION: EUV INSPECTION

- 10451 1D **Dark field technology for EUV and optical mask blank inspection** [10451-48]

POSTER SESSION: MATERIALS AND NOVEL APPLICATIONS

- 10451 1I **Laser-scan lithography and electrolytic etching for fabricating mesh structures on stainless-steel pipes 100µm in diameter** [10451-55]

POSTER SESSION: OPC

- 10451 1J **Automatic SRAF printing detection based on contour extraction** [10451-56]
- 10451 1K **Strategies on quantitative data preparation for OPC model calibration to reduce catastrophic failure at 7nm node** [10451-59]

POSTER SESSION: OPC/MASK INTERACTIONS

- 10451 1L **Aerial image ORC checks and their correlation to wafer-edge yield limitation for metals: a study and an OPC resolution [10451-61]**
- 10451 1M **Advanced process control based on litho-patterning density [10451-62]**
- 10451 1N **Improved testpatterns and coverage for complex SrAF to optimize 5nm and below OPC and mask patterning [10451-63]**

POSTER SESSION: PROCESS AND REPAIR

- 10451 1Q **Direct laser writing: virtual mask optimization for optical quality control artefact [10451-64]**
- 10451 1R **Dual-line fabrication method in direct laser lithography to reduce the manufacturing time of diffractive optics elements [10451-65]**
- 10451 1S **Transparent and conductive backside coating of EUV lithography masks for ultra short pulse laser correction [10451-66]**
- 10451 1T **Mask process correction method comparison and study: CD-SEM box versus standard correction method [10451-4]**
- 10451 1U **Micro-defect repair assisted with contour-based 2D metrology [10451-40]**